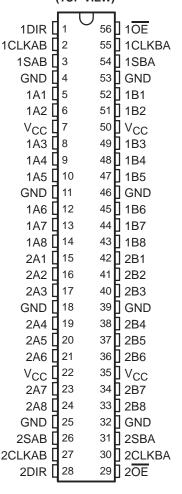
SCBS149D - JULY 1994 - REVISED MARCH 2004

- Members of the Texas Instruments Widebus™ Family
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low-Static Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Bus-Hold Data Inputs Eliminate the Need for External Pullup Resistors
- I_{off} and Power-Up 3-State Support Hot Insertion
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flowthrough Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

description/ordering information

The 'LVT16646 devices are 16-bit bus transceivers and registers designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

SN54LVT16646 . . . WD PACKAGE SN74LVT16646 . . . DGG OR DL PACKAGE (TOP VIEW)



These devices can be used as two 8-bit transceivers or one 16-bit transceiver. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'LVT16646 devices.

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	0000 01	Tube	SN74LVT16646DL	IV/T40040
-40°C to 85°C	SSOP – DL	Tape and reel	SN74LVT16646DLR	LVT16646
	TSSOP - DGG	Tape and reel	SN74LVT16646DGGR	LVT16646
-55°C to 125°C	CFP – WD	Tube	SNJ54LVT16646WD	SNJ54LVT16646WD

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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TEXAS INSTRUMENTS

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description/ordering information (continued)

Output-enable (\overline{OE}) and direction-control (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either register or in both. The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. The direction control (DIR) determines which bus receives data when \overline{OE} is low. In the isolation mode $(\overline{OE}$ high), A data may be stored in one register and/or B data may be stored in the other register.

When an output function is disabled, the input function is still enabled and may be used to store and transmit data. Only one of the two buses, A or B, may be driven at a time.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE

		INP	UTS			DATA	A I/Os	ODERATION OR FUNCTION
OE	DIR	CLKAB	CLKBA	SAB	SBA	A1 THRU A8	B1 THRU B8	OPERATION OR FUNCTION
Х	Х	1	Х	Х	Х	Input	Unspecified [†]	Store A, B unspecified [†]
X	X	Х	\uparrow	X	Χ	Unspecified [†]	Input	Store B, A unspecified [†]
Н	Х	1	↑	Х	Χ	Input	Input	Store A and B data
Н	X	H or L	H or L	X	Χ	Input disabled	Input disabled	Isolation, hold storage
L	L	Х	Χ	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	X	Н	Output	Input	Stored B data to A bus
L	Н	Х	Х	L	Χ	Input	Output	Real-time A data to B bus
L	Н	H or L	Χ	Н	Χ	Input	Output	Stored A data to B bus

[†] The data output functions may be enabled or disabled by various signals at $\overline{\text{OE}}$ and DIR. Data input functions always are enabled; i.e., data at the bus pins are stored on every low-to-high transition of the clock inputs.



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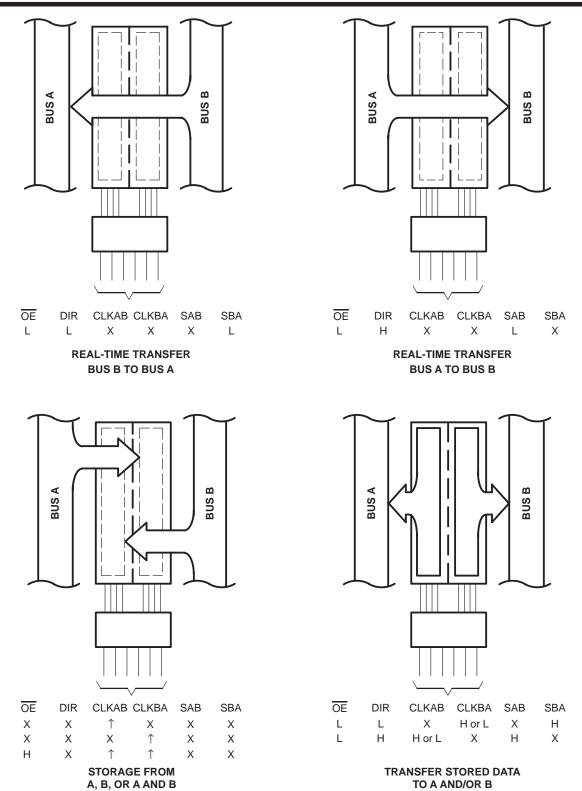
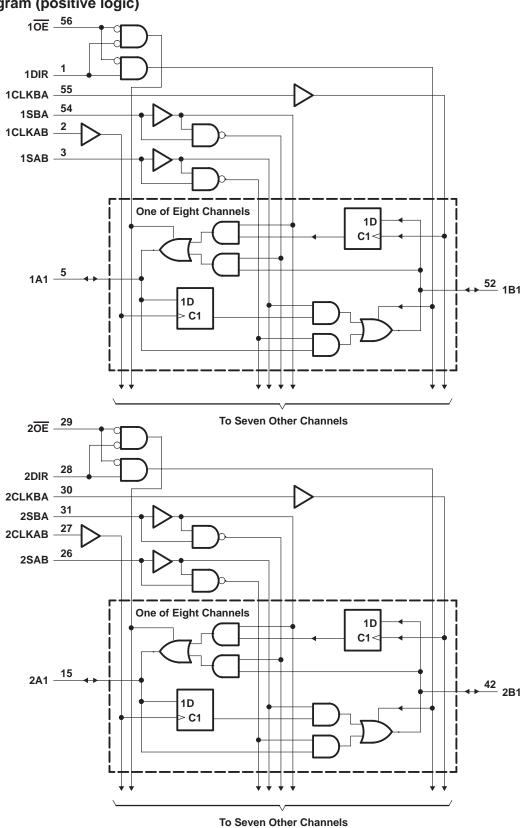


Figure 1. Bus-Management Functions



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logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the high state or power-off state, V _O (see Note 1) .	0.5 V to 7 V
Current into any output in the low state, IO: SN54LVT16646	96 mA
SN74LVT16646	128 mA
Current into any output in the high state, IO (see Note 2): SN54LVT16646	48 mA
SN74LVT16646	64 mA
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 3): DGG package	64°C/W
DL package	56°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			SN54LV	T16646	SN74LV	T16646	LINUT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2.7	3.6	2.7	3.6	V
VIH	High-level input voltage		2	FW	2		V
VIL	Low-level input voltage			0.8		0.8	V
VI	Input voltage			5.5		5.5	V
loh	High-level output current		Ç	-24		-32	mA
loL	Low-level output current		20	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	B	10		10	ns/V
TA	Operating free-air temperature	_	-55	125	-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	_	SNS	54LVT16	646	SN7	4LVT16	646				
PARAMETER	Т	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT			
VIK	$V_{CC} = 2.7 \text{ V},$	I _I = -18 mA				-1.2			-1.2	V	
	$V_{CC} = MIN \text{ to } MAX^{\ddagger},$	$I_{OH} = -100 \mu A$		VCC-0).2		VCC-0	.2			
M	$V_{CC} = 2.7 \text{ V},$	IOH = -8 mA		2.4			2.4				
VOH		$I_{OH} = -24 \text{ mA}$		2						V	
	VCC = 3 V	$I_{OH} = -32 \text{ mA}$					2				
	V 07V	$I_{OL} = 100 \mu A$				0.2			0.2		
	V _{CC} = 2.7 V	I _{OL} = 24 mA				0.5			0.5		
V		I _{OL} = 16 mA				0.4			0.4		
V_{OL}	0.4	I _{OL} = 32 mA				0.5			0.5	V	
	V _{CC} = 3 V	I _{OL} = 48 mA				0.55					
		I _{OL} = 64 mA				4			0.55		
	V _{CC} = 3.6 V,	$V_I = V_{CC}$ or GND	O and maliferent a		1	±1			±1		
	$V_{CC} = 0$ or MAX ‡ ,	V _I = 5.5 V	Control inputs		Q.	10			10	-	
lį		V _I = 5.5 V			6	20			20		
	V _{CC} = 3.6 V	VI = VCC	A or B ports§		30	5			5		
		V _I = 0	-10		-10	-10		-10			
l _{off}	$V_{CC} = 0$,	V_{I} or $V_{O} = 0$ to 4.5	V	¥					±100	μΑ	
		V _I = 0.8 V	A on D monto	75			75			Δ.	
l _(hold)	V _{CC} = 3 V	V _I = 2 V	A or B ports	-75			-75			μА	
lozh	$V_{CC} = 3.6 \text{ V},$	V _O = 3 V				1			1	μΑ	
IOZL	$V_{CC} = 3.6 \text{ V},$	V _O = 0.5 V				-1			-1	μΑ	
			Outputs high			0.12			0.12		
ICC	$V_{CC} = 3.6 \text{ V},$ $V_{I} = V_{CC} \text{ or GND}$	$I_{O} = 0,$	Outputs low			5			5	mA	
	ALT ACC OF GIAD		Outputs disabled			0.12			0.12		
ΔI _{CC} ¶	$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$ Other inputs at V_{CC} o	One input at V _{CC} · r GND			0.2			0.2	mA		
Ci	V _I = 3 V or 0				3.5			3.5		pF	
C _{io}	$V_O = 3 \text{ V or } 0$				12			12		pF	



[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$. ‡ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[§] Unused pins at V_{CC} or GND

This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

			SN54LVT16646				SN74LVT16646]
			V _{CC} =		VCC =	2.7 V	V _{CC} =		VCC =	2.7 V	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency			150	W.	150		150		150	MHz
t _W	Pulse duration, CLK high or low		3.3		3.3		3.3		3.3		ns
	Setup time,		1.3	Č	1.4		1.3		1.4		
tsu	A or B before CLKAB↑ or CLKBA↑	Data low	2.4	2	3		2.4		3		ns
. Hold	Hold time,	Data high	0.5	00	0		0.5		0		20
th	A or B after CLKAB↑ or CLKBA↑	Data low	0.6	Q.	0.5		0.5		0.5		ns

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 2)

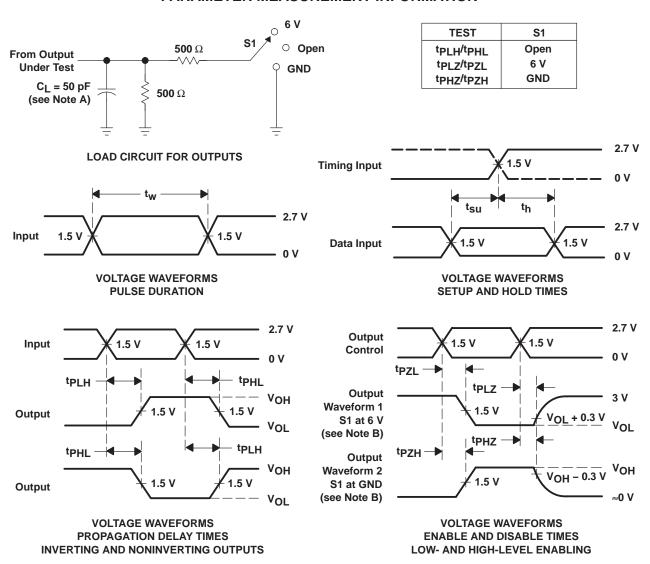
			SN54LVT16646				SN74LVT16646						
PARAMETER	FROM (INPUT)		TO (OUTPUT)	V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	MIN	TYP [†]	MAX	MIN	MAX		
f _{max}			150				150					MHz	
^t PLH	CLKBA or	A or D	1.8	6		6.9	1.8	3.8	5.7		6.7	20	
^t PHL	CLKAB	A or B	2.1	5.9		6.6	2.1	3.9	5.7		6.5	ns	
t _{PLH}	A == D	D A	1.3	4.9	2	5.6	1.3	3	4.7		5.4		
t _{PHL}	A or B	B or A	1	4.8	N/	5.8	1	3.1	4.7		5.6	ns	
t _{PLH}	SBA or SAB‡		1.4	6.4	34	7.4	1.4	4	6.2		7.2		
t _{PHL}	SBA OF SAB+	A or B	1.4	6.4	7,	7.4	1.4	4.3	6.2		7.2	ns	
^t PZH	ŌĒ		1	5.7)	7.4	1	3	5.4		6.4		
tPZL	OE	A or B	1	6.5		7.5	1	3.1	5.6		6.5	ns	
^t PHZ	ŌĒ	A D	2.3	6.7		7.1	2.3	4.6	6.5		6.9		
^t PLZ	OE	A or B	2.2	6		6.5	2.2	4.5	5.8		5.9	ns	
^t PZH	55	A D	1	5.9		7.7	1	3.3	5.7		6.7		
tpzL	DIR	A or B	1.2	5.9		7.3	1.2	3.5	5.8		6.7	ns	
^t PHZ	DIR	A or P	1.7	7.3		8.5	1.7	4.7	7.2		8.3	20	
t _{PLZ}	DIK	A or B	1.5	7.8		7.4	1.5	4.9	6.6		7.2	ns	

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡]These parameters are measured with the internal output state of the storage register opposite to that of the bus input.

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \,\Omega_{1}$ t_r \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVT16646DGGR	ACTIVE	TSSOP	DGG	56	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LVT16646DL	ACTIVE	SSOP	DL	56	20	TBD	CU NIPDAU	Level-1-235C-UNLIM
SN74LVT16646DLR	NRND	SSOP	DL	56	1000	TBD	CU NIPDAU	Level-1-235C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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